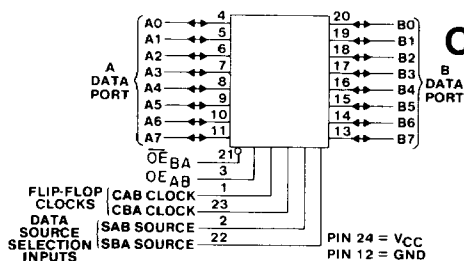


CD54/74AC651, CD54/74AC652

CD54/74ACT651, CD54/74ACT652

Advance Information



FUNCTIONAL DIAGRAM

92CS-42677

Octal-Bus Transceiver/Registers, 3-State

CD54/74AC/ACT651 - Inverting

CD54/74AC/ACT652 - Non-Inverting

Type Features:

- Buffered inputs
- Typical propagation delay:
5.3 ns @ $V_{CC} = 5V$, $T_A = 25^\circ C$, $C_L = 50 pF$

Family Features:

- Exceeds 2-kV ESD Protection - MIL-STD-883, Method 3015
- SCR-Latchup-resistant CMOS process and circuit design
- Speed of bipolar FAST*/AS/S with significantly reduced power consumption
- Balanced propagation delays
- AC types feature 1.5-V to 5.5-V operation and balanced noise immunity at 30% of the supply
- ± 24 -mA output drive current
 - Fanout to 15 FAST* ICs
 - Drives 50-ohm transmission lines

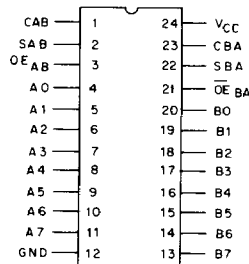
*FAST is a Registered Trademark of Fairchild Semiconductor Corp.

The RCA CD54/74AC651 and CD54/74AC652 and the CD54/74ACT651 and CD54/74ACT652 3-state, octal-bus transceiver/registers use the RCA ADVANCED CMOS technology. The CD54/74AC651 and CD54/74ACT651 have inverting outputs. The CD54/74AC652 and CD54/74ACT652 have non-inverting outputs. These devices consist of bus transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. Output Enables OE_{AB} and OE_{BA} are provided to control the transceiver functions. SAB and SBA control pins are provided to select whether real-time or stored data is transferred. The circuitry used for select control will eliminate the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. A LOW input level selects real-time data, and a HIGH selects stored data. The following examples demonstrate the four fundamental bus-management functions that can be performed with the octal-bus transceivers and registers.

Data on the A or B data bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock pins (CAB or CBA) regardless of the select or enable control pins. When SAB and SBA are in the real-time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling OE_{AB} and OE_{BA} . In this configuration, each output reinforces its input. Thus, when all other data sources to the two sets of bus lines are at high impedance, each set of bus lines will remain at its last state.

The CD74AC/ACT651 and CD74AC/ACT652 are supplied in 24-lead dual-in-line narrow-body plastic packages (EN suffix) and in 24-lead dual-in-line small-outline plastic packages (M suffix). Both package types are operable over the following temperature ranges: Commercial (0 to $70^\circ C$); Industrial (-40 to $+85^\circ C$); and Extended Industrial/Military (-55 to $+125^\circ C$).

The CD54AC/ACT651 and CD54AC/ACT652, available in chip form (H suffix), are operable over the -55 to $+125^\circ C$ temperature range.



92CS-42678

TERMINAL ASSIGNMENT

CD54/74AC651, CD54/74AC652

CD54/74ACT651, CD54/74ACT652

FUNCTION TABLE

INPUTS						DATA I/O		OPERATION OR FUNCTION	
OE _{AB}	OE _{BA}	CAB	CBA	SAB	SBA	A0 THRU A7	B0 THRU B7	651	652
L	H	H or L	H or L	X	X	Input	Input	Isolation *	Isolation*
L	H			X	X	Input	Input	Store A and B Data	Store A and B Data
X	H		H or L	X	X	Input	Unspecified†	Store A, Hold B	Store A, Hold B
H	H			X‡	X	Input	Output	Store A in both registers	Store A in both registers
L	X	H or L		X	X	Unspecified†	Input	Hold A, Store B	Hold, A Store B
L	L			X	X‡	Output	Input	Store B in both registers	Store B in both registers
L	L	X	X	X	L	Output	Input	Real-Time B̄ Data to A Bus	Real-Time B̄ Data to A Bus
L	L	X	H or L	X	H	Output	Input	Stored B̄ Data to A Bus	Stored B̄ Data to A Bus
H	H	X	X	L	X	Input	Output	Real-Time Ā Data to B Bus	Real-Time Ā Data to B Bus
H	H	H or L	X	H	X	Input	Output	Stored Ā Data to B Bus	Stored Ā Data to B Bus
H	L	H or L	H or L	H	H	Output	Output	Stored Ā Data to B Bus and Stored B̄ Data to A bus	Stored A Data to B Bus Stored B Data to A Bus

* To prevent excess currents in the High-Z (isolation) modes, all I/O terminals should be terminated with 10kΩ to 1MΩ resistors.

† The data output functions may be enabled or disabled by various signals at the OE_{AB} or OE_{BA} inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every low-to-high transition on the clock inputs.

‡ Select control = L: clocks can occur simultaneously.

Select control = H: clocks must be staggered in order to load both registers.

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE (V_{CC}) -0.5 to 6 V

DC INPUT DIODE CURRENT, I_{IK} (for $V_i < -0.5$ V or $V_i > V_{CC} + 0.5$ V) ±20 mA

DC OUTPUT DIODE CURRENT, I_{OK} (for $V_o < -0.5$ V or $V_o > V_{CC} + 0.5$ V) ±50 mA

DC OUTPUT SOURCE OR SINK CURRENT per Output Pin, I_o (for $V_o > -0.5$ V or $V_o < V_{CC} + 0.5$ V) ±50 mA

DC V_{CC} or GROUND CURRENT (I_{CC} or I_{GND}) ±100 mA*

POWER DISSIPATION PER PACKAGE (P_D):

For $T_A = -55$ to $+100^\circ\text{C}$ (PACKAGE TYPE E) 500 mW

For $T_A = +100$ to $+125^\circ\text{C}$ (PACKAGE TYPE E) Derate Linearly at 8 mW/ $^\circ\text{C}$ to 300 mW

For $T_A = -55$ to $+70^\circ\text{C}$ (PACKAGE TYPE M) 400 mW

For $T_A = +70$ to $+125^\circ\text{C}$ (PACKAGE TYPE M) Derate Linearly at 6 mW/ $^\circ\text{C}$ to 70 mW

OPERATING-TEMPERATURE RANGE (T_A) -55 to $+125^\circ\text{C}$

STORAGE TEMPERATURE (T_{STG}) -65 to $+150^\circ\text{C}$

LEAD TEMPERATURE (DURING SOLDERING):

At distance 1/16 ± 1/32 in. (1.59 ± 0.79 mm) from case for 10 s maximum +265°C

Unit inserted into PC board min. thickness 1/16 in. (1.59 mm) with solder contacting lead tips only +300°C

*For up to 4 outputs per device; add ± 25 mA for each additional output.

RECOMMENDED OPERATING CONDITIONS:

For maximum reliability, normal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTICS	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range, V_{CC} †: (For T_A = Full Package-Temperature Range) AC Types ACT Types	1.5 4.5	5.5 5.5	V V
DC Input or Output Voltage, V_i , V_o	0	V_{CC}	V
Operating Temperature, T_A	-55	+125	°C
Input Rise and Fall Slew Rate, dt/dv at 1.5 V to 3 V (AC Types) at 3.6 V to 5.5 V (AC Types) at 4.5 V to 5.5 V (ACT Types)	0 0 0	50 20 10	ns/V ns/V ns/V

*Unless otherwise specified, all voltages are referenced to ground.

CD54/74AC651, CD54/74AC652

CD54/74ACT651, CD54/74ACT652

STATIC ELECTRICAL CHARACTERISTICS: AC Series

CHARACTERISTICS	TEST CONDITIONS		V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C						UNITS	
				+25		-40 to +85		-55 to +125			
	V _I (V)	I _O (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
High-Level Input Voltage	V _{IH}		1.5 3 5.5	1.2 2.1 3.85	— — —	1.2 2.1 3.85	— — —	1.2 2.1 3.85	— — —	V	
Low-Level Input Voltage	V _{IL}		1.5 3 5.5	— — —	0.3 0.9 1.65	— — —	0.3 0.9 1.65	— — —	0.3 0.9 1.65	V	
High-Level Output Voltage	V _{OH}	V _{IH} or V _{IL} # , * }	-0.05	1.5	1.4	—	1.4	—	1.4	—	V
			-0.05	3	2.9	—	2.9	—	2.9	—	
			-0.05	4.5	4.4	—	4.4	—	4.4	—	
			-4	3	2.58	—	2.48	—	2.4	—	
			-24	4.5	3.94	—	3.8	—	3.7	—	
			-75	5.5	—	—	3.85	—	—	—	
Low-Level Output Voltage	V _{OL}	V _{IH} or V _{IL} # , * }	-50	5.5	—	—	—	—	3.85	—	V
			0.05	1.5	—	0.1	—	0.1	—	0.1	
			0.05	3	—	0.1	—	0.1	—	0.1	
			0.05	4.5	—	0.1	—	0.1	—	0.1	
			12	3	—	0.36	—	0.44	—	0.5	
			24	4.5	—	0.36	—	0.44	—	0.5	
Input Leakage Current	I _I	V _{CC} or GND		5.5	—	±0.1	—	±1	—	±1	μA
3-State Leakage Current	I _{OZ}	V _{IH} or V _{IL} V _O = V _{CC} or GND		5.5	—	±0.5	—	±5	—	±10	μA
Quiescent Supply Current, MSI	I _{CC}	V _{CC} or GND	0	5.5	—	8	—	80	—	160	μA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

CD54/74AC651, CD54/74AC652

CD54/74ACT651, CD54/74ACT652

STATIC ELECTRICAL CHARACTERISTICS: ACT Series

CHARACTERISTICS	TEST CONDITIONS		V_{CC} (V)	AMBIENT TEMPERATURE (T_A) - °C						UNITS
				+25		-40 to +85		-55 to +125		
	V_I (V)	I_O (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage V_{IH}			4.5 to 5.5	2	—	2	—	2	—	V
Low-Level Input Voltage V_{IL}			4.5 to 5.5	—	0.8	—	0.8	—	0.8	V
High-Level Output Voltage V_{OH}	V_{IH} or V_{IL} #, * }	-0.05	4.5	4.4	—	4.4	—	4.4	—	V
		-24	4.5	3.94	—	3.8	—	3.7	—	
		-75	5.5	—	—	3.85	—	—	—	
		-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage V_{OL}	V_{IH} or V_{IL} #, * }	0.05	4.5	—	0.1	—	0.1	—	0.1	V
		24	4.5	—	0.36	—	0.44	—	0.5	
		75	5.5	—	—	—	1.65	—	—	
		50	5.5	—	—	—	—	—	1.65	
Input Leakage Current I_I	V_{CC} or GND		5.5	—	±0.1	—	±1	—	±1	μA
3-State Leakage Current I_{OZ}	V_{IH} or V_{IL} $V_O = V_{CC}$ or GND		5.5	—	±0.5	—	±5	—	±10	μA
Quiescent Supply Current, MSI I_{CC}	V_{CC} or GND	0	5.5	—	8	—	80	—	160	μA
Additional Quiescent Supply Current per Input Pin TTL Inputs High 1 Unit Load ΔI_{CC}	$V_{CC}-2.1$		4.5 to 5.5	—	2.4	—	2.8	—	3	mA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

*Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

ACT INPUT LOADING TABLE

INPUT	UNIT LOAD*
CAB, CBA	1.25
SAB, SBA	1.2
OE _{AB}	0.67
OE _{BA}	1.17
An, Bn	0.4

*Unit load is ΔI_{CC} limit specified in Static Characteristics Chart, e.g., 2.4 mA max. @ 25°C.

CD54/74AC651, CD54/74AC652 **CD54/74ACT651, CD54/74ACT652**

PREREQUISITE FOR SWITCHING: AC Series

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Max. Frequency	f _{max}	1.5 3.3* 5†	11 101 143	— — —	10 89 125	— — —	MHz
Setup Time Data to Clock	t _{su}	1.5 3.3 5	27 3.1 2.2	— — —	31 3.5 2.5	— — —	ns
Hold Time Data to Clock	t _h	1.5 3.3 5	2 2 2	— — —	2 2 2	— — —	ns
Clock Pulse Data to Clock	t _w	1.5 3.3 5	44 4.9 3.5	— — —	50 5.6 4	— — —	ns

*3.3 V: min. is @ 3 V

†5 V: min. is @ 4.5 V

SWITCHING CHARACTERISTICS: AC Series; t_r, t_f = 3 ns, C_L = 50 pF

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Store A Data to B Bus Store B Data to A Bus 652	t _{PLH} t _{PHL}	1.5 3.3* 5†	— 4.8 3.5	154 17.1 12.3	— 4.7 3.4	169 18.9 13.5	ns
Store A Data to B Bus Store B Data to A Bus 651	t _{PLH} t _{PHL}	1.5 3.3 5	— 4.8 3.5	154 17.1 12.3	— 4.7 3.4	169 18.9 13.5	ns
A Data to B Bus B Data to A Bus 652	t _{PLH} t _{PHL}	1.5 3.3 5	— 4 2.8	125 14 10	— 3.9 2.8	138 15.4 11	ns
A Data to B Bus B Data to A Bus 651	t _{PLH} t _{PHL}	1.5 3.3 5	— 4 2.8	125 14 10	— 3.9 2.8	138 15.4 11	ns
Select to Data 652	t _{PLH} t _{PHL}	1.5 3.3 5	— 4.3 3.1	136 15.3 10.9	— 4.2 3	150 16.8 12	ns
Select to Data 651	t _{PLH} t _{PHL}	1.5 3.3 5	— 4.3 3.1	136 15.3 10.9	— 4.2 3	150 16.8 12	ns
3-State Enabling/ Disabling Time Bus to Output or Register to Output	t _{PZL} t _{PZH} t _{PLZ} t _{PHZ}	1.5 3.3 5	— 5.2 3.5	154 18.4 12.3	— 5.1 3.4	169 20.2 13.5	ns
Power Dissipation Capacitance	C _{PD} §	—	150 Typ.		150 Typ.		pF
Min. (Valley) During Switching of Other Outputs (Output Under Test Not Switching)	V _{OH} V _{OHV} See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) During Switching of Other Outputs (Output Under Test Not Switching)	V _{OL} V _{OLP} See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C _I	—	—	10	—	10	pF
3-State Output Capacitance	C _O	—	—	15	—	15	pF

*3.3 V: min. is @ 3.6 V
max. is @ 3 V

†5 V: min. is @ 5.5 V
max. is @ 4.5 V

§C_{PD} is used to determine the dynamic power consumption, per package.

P_D = V_{CC}² C_{PD} f_i + Σ (V_{CC}² C_L f_o) where f_i = input frequency

f_o = output frequency

C_L = output load capacitance

V_{CC} = supply voltage.

CD54/74AC651, CD54/74AC652

CD54/74ACT651, CD54/74ACT652

PREREQUISITE FOR SWITCHING: ACT Series

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Max. Frequency	f _{max}	5*	125	—	110	—	MHz
Setup Time Data to Clock	t _{SU}	5	2.2	—	2.5	—	ns
Hold Time Data to Clock	t _H	5	2	—	2	—	ns
Clock Pulse Width	t _W	5	3.9	—	4.5	—	ns

*5 V: min. is @ 4.5 V

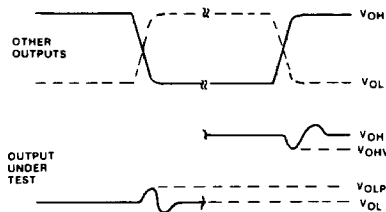
SWITCHING CHARACTERISTICS: ACT Series; $t_r, t_f = 3$ ns, $C_L = 50$ pF

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Store A Data to B Bus Store B Data to A Bus 652	t _{PLH} t _{PHL}	5*	4	14.1	3.9	15.5	ns
Store A Data to B Bus Store B Data to A Bus 651	t _{PLH} t _{PHL}	5	4	14.1	3.9	15.5	ns
A Data to B Bus B Data to A Bus 652	t _{PLH} t _{PHL}	5	3.2	11.4	3.1	12.5	ns
A Data to B Bus B Data to A Bus 651	t _{PLH} t _{PHL}	5	3.2	11.4	3.1	12.5	ns
Select to Data 652	t _{PLH} t _{PHL}	5	3.7	13.2	3.6	14.5	ns
Select to Data 651	t _{PLH} t _{PHL}	5	4	14.1	3.9	15.5	ns
3-State Enabling/ Disabling Time Bus to Output or Register to Output	t _{PZL} t _{PZH} t _{PLZ} t _{PHZ}	5	4	14.1	3.9	15.5	ns
Power Dissipation Capacitance	C _{PD}	—	150 Typ.		150 Typ.		pF
Min. (Valley) During Switching of Other Outputs (Output Under Test Not Switching)	V _{OH} V _{OHV} See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) During Switching of Other Outputs (Output Under Test Not Switching)	V _{OL} V _{OLP} See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C _I	—	—	10	—	10	pF
3-State Output Capacitance	C _O	—	—	15	—	15	pF

*5 V: min. is @ 5.5 V
max. is @ 4.5 V $\S C_{PD}$ is used to determine the dynamic power consumption, per package.
$$P_D = V_{CC}^2 C_{PD} f_i + \sum V_{CC}^2 C_L f_o + V_{CC} \Delta I_{CC}$$

where f_i = input frequency
 f_o = output frequency
 C_L = output load capacitance
 V_{CC} = supply voltage.

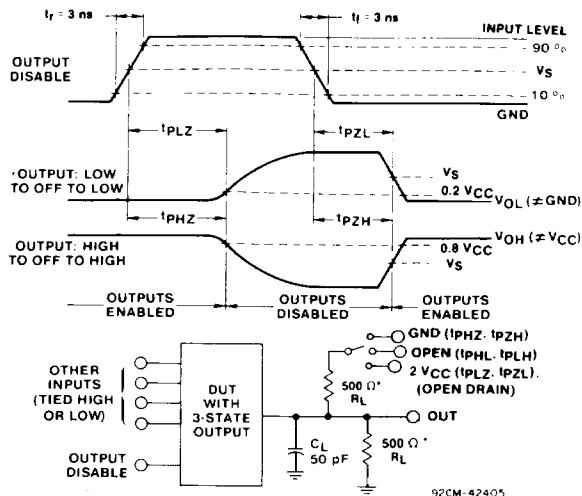
CD54/74AC651, CD54/74AC652 CD54/74ACT651, CD54/74ACT652



- NOTES:
1. V_{OHV} and V_{OLP} are measured with respect to a ground reference near the output under test.
 2. INPUT PULSES HAVE THE FOLLOWING CHARACTERISTICS:
PRR = 1 MHz; t_r = 3 ns; t_f = 3 ns; SKEW 1 ns.
 3. R.F. FIXTURE WITH 700-MHz DESIGN RULES REQUIRED.
IC SHOULD BE SOLDERED INTO TEST BOARD AND BYPASSED WITH 0.1 μ F CAPACITOR. SCOPE AND PROBES REQUIRE 700-MHz BANDWIDTH.

92CS-42406

Fig. 1 - Simultaneous switching transient waveforms.



*FOR AC SERIES ONLY: WHEN $V_{CC} = 1.5$ V, $R_L = 1$ k Ω

Fig. 2 - Three-state propagation delay waveforms and test circuit.

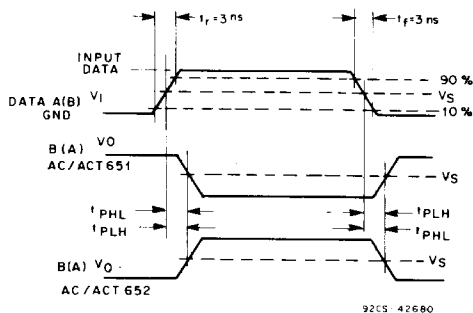


Fig. 3 - Propagation delay times.

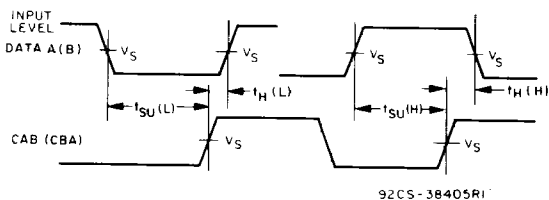
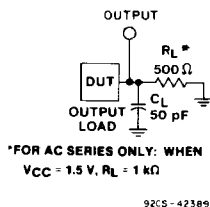


Fig. 4 - Data setup and hold times.



*FOR AC SERIES ONLY: WHEN
 $V_{CC} = 1.5$ V, $R_L = 1$ k Ω

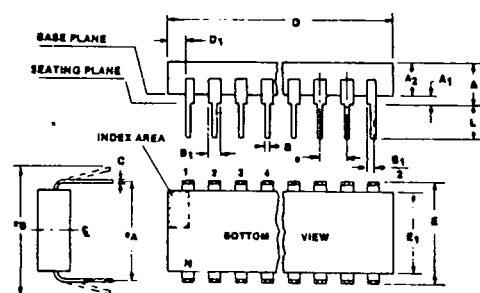
92CS-42389

Fig. 5 - Test circuit.

	CD54/74AC	CD54/74ACT
Input Level	V_{CC}	3 V
Input Switching Voltage, V_S	0.5 V_{CC}	1.5 V
Output Switching Voltage, V_S	0.5 V_{CC}	0.5 V_{CC}

Dual-In-Line Plastic Packages

T-90-20

(E) Suffix (JEDEC MS-001-AC)
14-Lead Dual-In-Line Plastic Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	—	0.210	—	5.33	9
A ₁	0.015	—	0.39	—	9
A ₂	0.115	0.195	2.93	4.95	
B	0.014	0.022	0.356	0.558	
B ₁	0.045	0.070	1.15	1.77	3
C	0.008	0.015	0.204	0.381	
D	0.725	0.795	18.42	20.19	4
D ₁	0.005	—	0.13	—	12
E	0.300	0.325	7.62	8.25	5
E ₁	0.240	0.280	6.10	7.11	6, 7
e	0.100 BSC		2.54 BSC		8
e _A	0.300 BSC		7.62 BSC		9
e _B	—	0.430	—	10.92	10
L	0.115	0.160	2.93	4.06	9
N	14		14		11

92CS-39901

(E) Suffix (JEDEC MS-001-AA)
16-Lead Dual-In-Line Plastic Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	—	0.210	—	5.33	9
A ₁	0.015	—	0.39	—	9
A ₂	0.115	0.195	2.93	4.95	
B	0.014	0.022	0.356	0.558	
B ₁	0.045	0.070	1.15	1.77	3
C	0.008	0.015	0.204	0.381	
D	0.745	0.840	18.93	21.33	4
D ₁	0.005	—	0.13	—	12
E	0.300	0.325	7.62	8.25	5
E ₁	0.240	0.280	6.10	7.11	6, 7
e	0.100 BSC		2.54 BSC		8
e _A	0.300 BSC		7.62 BSC		9
e _B	—	0.430	—	10.92	10
L	0.115	0.160	2.93	4.06	9
N	16		16		11

92CS-39900

Notes:

1. Refer to JEDEC Publication No. 95 JEDEC Registered and Standard Outlines for Solid State Products, for rules and general information concerning registered and standard outlines, in Section 2.2.
2. Protrusions (flash) on the base plane surface shall not exceed 0.010 in. (0.25 mm).
3. The dimension shown is for full leads. "Half" leads are optional at lead positions

$$1, N, \frac{N}{2}, \frac{N}{2} + 1.$$
4. Dimension D does not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 in. (0.25 mm).
5. E is the dimension to the outside of the leads and is measured with the leads perpendicular to the base plane (zero lead spread).
6. Dimension E₁ does not include mold flash or protrusions.
7. Package body and leads shall be symmetrical around center line shown in end view.
8. Lead spacing e shall be non-cumulative and shall be measured at the lead lip. This measurement shall be made before insertion into gauges, boards or sockets.
9. This is a basic installed dimension. Measurement shall be made with the device installed in the seating plane gauge (JEDEC Outline No. GS-3, seating plane gauge). Leads shall be in true position within 0.010 in. (0.25 mm) diameter for dimension e_A.
10. e_B is the dimension to the outside of the leads and is measured at the lead tips before the device is installed. Negative lead spread is not permitted.
11. N is the maximum number of lead positions.
12. Dimension D₁ at the left end of the package must equal dimension D₁ at the right end of the package within 0.030 in. (0.76 mm).
13. For automatic insertion, any raised irregularity on the top surface (step, mesa, etc.) shall be symmetrical about the lateral and longitudinal package centerlines.

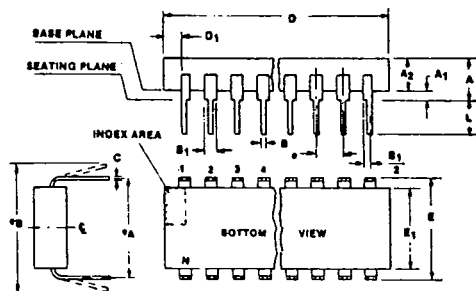
(E) Suffix (JEDEC MS-001-AE)
20-Lead Dual-In-Line Plastic Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	—	0.210	—	5.33	9
A ₁	0.015	—	0.39	—	9
A ₂	0.115	0.195	2.93	4.95	
B	0.014	0.022	0.356	0.558	
B ₁	0.045	0.070	1.15	1.77	3
C	0.008	0.015	0.204	0.381	
D	0.925	1.060	23.5	26.9	4
D ₁	0.005	—	0.13	—	12
E	0.300	0.325	7.62	8.25	5
E ₁	0.240	0.280	6.10	7.11	6, 7
e	0.100 BSC		2.54 BSC		8
e _A	0.300 BSC		7.62 BSC		9
e _B	—	0.430	—	10.92	10
L	0.115	0.160	2.93	4.06	9
N	20		20		11

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Dual-In-Line Plastic Packages

T-90-20

(E) Suffix (JEDEC MS-001-AF)
24-Lead Dual-In-Line Plastic Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	—	0.210	—	5.33	9
A ₁	0.015	—	0.39	—	9
A ₂	0.115	0.195	2.93	4.95	
B	0.014	0.022	0.356	0.558	
B ₁	0.045	0.070	1.15	1.77	3
C	0.008	0.015	0.204	0.381	
D	1.125	1.275	28.6	32.3	4
D ₁	0.005	—	0.13	—	12
E	0.300	0.325	7.62	8.25	5
E ₁	0.240	0.280	6.10	7.11	6, 7
e	0.100 BSC		2.54 BSC		8
e _A	0.300 BSC		7.62 BSC		9
e _B	—	0.430	—	10.92	10
L	0.115	0.160	2.93	4.06	9
N	24		24		11

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Notes:

1. Refer to JEDEC Publication No. 95 JEDEC Registered and Standard Outlines for Solid State Products, for rules and general information concerning registered and standard outlines, in Section 2.2.
2. Protrusions (flash) on the base plane surface shall not exceed 0.010 in. (0.25 mm).
3. The dimension shown is for full leads. "Half" leads are optional at lead positions

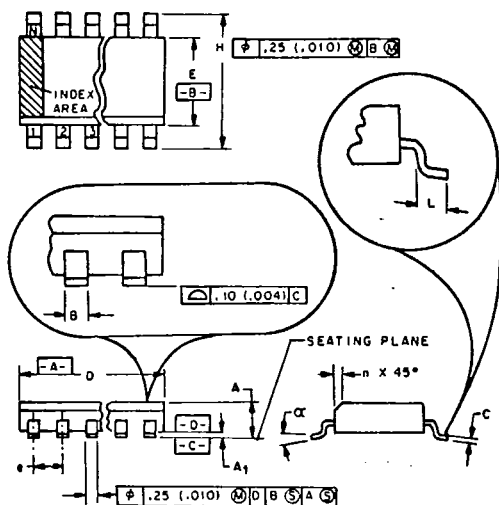
$$1, N, \frac{N}{2}, \frac{N}{2} + 1.$$
4. Dimension D does not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 in. (0.25 mm).
5. E is the dimension to the outside of the leads and is measured with the leads perpendicular to the base plane (zero lead spread).
6. Dimension E₁ does not include mold flash or protrusions.
7. Package body and leads shall be symmetrical around

center line shown in end view.

8. Lead spacing e shall be non-cumulative and shall be measured at the lead lip. This measurement shall be made before insertion into gauges, boards or sockets.
9. This is a basic installed dimension. Measurement shall be made with the device installed in the seating plane gauge (JEDEC Outline No. GS-3, seating plane gauge). Leads shall be in true position within 0.010 in. (0.25 mm) diameter for dimension e_A.
10. e_B is the dimension to the outside of the leads and is measured at the lead tips before the device is installed. Negative lead spread is not permitted.
11. N is the maximum number of lead positions.
12. Dimension D₁ at the left end of the package must equal dimension D₁ at the right end of the package within 0.030 in. (0.76 mm).
13. For automatic insertion, any raised irregularity on the top surface (step, mesa, etc.) shall be symmetrical about the lateral and longitudinal package centerlines.

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Dual-In-Line Small-Outline Plastic Packages



NOTES:

1. Refer to applicable symbol list.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. "D" is a reference datum.
4. "A" and "B" are reference datums and do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm (0.006 in.).
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the cross-hatched area.
6. "L" is the length of terminal for soldering to a substrate.
7. "N" is the number of terminal positions.
8. Terminal numbers are shown for reference only.
9. Controlling dimensions: MILLIMETERS.

M Suffix (JEDEC MS-012AB)

14-Lead Dual-In-Line Small-Outline (SO) Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	0.0532	0.0688	1.35	1.75	
A ₁	0.0040	0.0098	0.10	0.25	
B	0.0138	0.020	0.35	0.508	
C	0.0075	0.0098	0.19	0.25	
D	0.3367	0.3444	8.55	8.75	4
E	0.1497	0.1574	3.80	4.00	4
e	0.050 BSC		1.27 BSC		
H	0.2284	0.2440	5.80	6.20	
h	0.0099	0.0196	0.25	0.50	5
L	0.016	0.050	0.40	1.27	6
N	14		14		7
α	0°	8°	0°	8°	

Notes: 1, 2, 3, 8, 9

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M Suffix (JEDEC MS-012AC)

16-Lead Dual-In-Line Small-Outline (SO) Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	0.0532	0.0688	1.35	1.75	
A ₁	0.0040	0.0098	0.10	0.25	
B	0.0138	0.020	0.35	0.508	
C	0.0075	0.0098	0.19	0.25	
D	0.3859	0.3937	9.80	10.00	4
E	0.1497	0.1574	3.80	4.00	4
e	0.050 BSC		1.27 BSC		
H	0.2284	0.2440	5.80	6.20	
h	0.0099	0.0196	0.25	0.50	5
L	0.016	0.050	0.40	1.27	6
N	16		16		7
α	0°	8°	0°	8°	

Notes: 1, 2, 3, 8, 9

92CS-38925R2

M Suffix (JEDEC MS-013AC)

20-Lead Dual-In-Line Small-Outline (SO) Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	0.0926	0.1043	2.35	2.65	
A ₁	0.0040	0.0118	0.10	0.30	
B	0.0138	0.020	0.35	0.508	
C	0.0091	0.0125	0.23	0.32	
D	0.4861	0.5118	12.60	13.00	4
E	0.2914	0.2992	7.40	7.60	4
e	0.050 BSC		1.27 BSC		
H	0.394	0.419	10.00	10.65	
h	0.010	0.029	0.25	0.75	5
L	0.016	0.050	0.40	1.27	6
N	20		20		7
α	0°	8°	0°	8°	

Notes: 1, 2, 3, 8, 9

92CS-38926R2

M Suffix (JEDEC MS-013AD)

24-Lead Dual-In-Line Small-Outline (SO) Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	0.0926	0.1043	2.35	2.65	
A ₁	0.0040	0.0118	0.10	0.30	
B	0.0138	0.020	0.35	0.508	
C	0.0091	0.0125	0.23	0.32	
D	0.5985	0.6141	15.20	15.60	4
E	0.2914	0.2992	7.40	7.60	4
e	0.050 BSC		1.27 BSC		
H	0.394	0.419	10.00	10.65	
h	0.010	0.029	0.25	0.75	5
L	0.016	0.050	0.40	1.27	6
N	24		24		7
α	0°	8°	0°	8°	

Notes: 1, 2, 3, 8, 9

92CS-39037R2